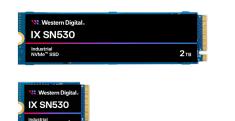


PRODUCT BRIEF



Product Highlights

- High performance at industrial-grade temperatures -40°C to +85°C
- Up to 2TB in M.2 2280 and up to 1TB in M.2 2230
- Available in TLC and SLC configurations

Applications

- Industrial PCs
- Factory automation
- Robotics
- Fanless designs
- Digital signage
- Data logging and boot device for autonomous driving systems

Western Digital® IX SN530 NVMe[™] Industrial-Grade SSD

Empowering a new generation of data-rich industrial and autonomous driving designs

Western Digital IX SN530 NVMe industrial-grade SSD (IX SN530) offers a high-performance, wide-temperature range storage solution designed for the demanding requirements of industrial and autonomous driving applications. With flexibility through high-capacity TLC and high-endurance SLC options, the IX SN530 offers two M.2 form factors and up to 2TB² of storage space.

Built for Extreme Conditions

The IX SN530 supports a wide range of environmental conditions, including operating temperatures and shock and vibration, which allow it to be used in systems placed in various physical locations in a vehicle or other equipment, enabling placement flexibility for system designers.

Robust and Reliable Design

A fully vertically integrated solid state drive, the IX SN530 is built with Western Digital's 96-layer 3D NAND technology, in-house controller and firmware development, internal validation and qualification, and extensive testing; making it ideal for handling a wide variety of industrial and automotive use cases. In addition, Western Digital supports five-year longevity with controlled bill-of-material and provides product change notifications, for customers' peace of mind.

Further, by offering SLC configurations, the IX SN530 supports write-intensive applications, such as data recorder and data set management, saving the need to use multiple high-capacity TLC devices by delivering 9 times the TLC endurance and up to 5 times the TLC sustained write performance.

Gearing Up with NVMe SSDs

The IX SN530 is available in two M.2 form factors—a compact M.2 2230 and M.2 2280 addressing a variety of system designs and mechanical constraints. This compact solution helps to reduce maintenance costs and enhance serviceability, making the transition to industrial-grade PCIe NVMe SSDs easier.

Specifications

-								
Generic Specifications								
Interface ¹				PCIe Gen3 x4 NVMe v1	1.4			
Form factors	M.2 228			-M / M.2 2230-S3-M			M.2 2280-S3-M	
3D NAND flash		SLC 96-layer			TLC	96-layer		
Capacity ²	85GB	170GB	340GB	256GB	512GB	1TB	2TB	
Performance								
Sequential Read up to (MB/s) ³	2,400	2,400	2,400	2,400	2,400	2,400	2,500	
Burst Sequential Write up to (MB/s) ⁴	900	1,750	1,950	900	1,750	1,950	1,800	
Sustained Sequential Write up to (MB/s) ³	900	1,750	1,950	140	280	540	525	
Random Read up to (IOPS) ³	160K	310K	410K	160K	310K	410K	370K	
Random Write up to (IOPS) ³	180K	330K	350K	85K	150K	350K	300K	
Power (projected)								
Average Power (W) ⁵	3.3	3.3	3.5	3.5	3.5	3.5	3.9	
Peak Power (W) ⁶	5.5	5.5	5.5	5.5	5.5	5.5	5.5	
Reliability								
Endurance (TBW) ⁷ (projected) Mean Time To Failure (MTTF) ⁸	6,000	12,000	24,000	650	1,300	2,600	5,200	
(Hours) (projected)								
Unrecoverable Bit Error Rate (UBER)	1 error per 10 ¹⁶ bits read							
Data Retention (EOL)	1 year at +55°C							
Environmental								
Operating Temperature ⁹	-40°C to +85°C							
Non-Operating Temperature	-40°C to +95°C							
Operating Vibration	20GRMS, 7 to 2,000Hz, 30min/axis on 3 axes							
Shock	1,500G, 0.5ms Half Sine pulse duration							
Altitude	-1500ft (-457m) to 40,000ft (12,192m)							
Certifications	FCC, CE, UL, TU	V, BSMI, KCC, RCM,	Morocco, VCCI an	d CAN ICES-3(B)/NMB-3	3(B)	_		
Advanced Features								
 Functional DRAMless architecture with Host Memory Buffer (HMB) support. 	-			Dynamic and static wear-leveling, • TCG			rity G Pyrite security support for sword protection (ATA-like).	
 nCache 3.0 SLC tiered caching technology. 	DSP capabilities in hardware. • NAND XOR protection for multi-page recovery. • Automatic Data Refresh. • NVMe S.M.A.R.T.			ackground garbage col	llection.	Secure Boot including authentication and so firmware upgrade.		
Physical Dimensions								
Weight typical (gr)			2230: 3.2 ± 0	0.5 / 2280: 7.5 ± 1.0			2280: 7.5 ± 1.0	
Width (mm) ¹⁰	2230: 22 ± 0.15 / 2280: 22 ± 0.15						2280: 22 ± 0.15	
Length (mm) ¹⁰	2230: 30 ± 0.15 / 2280: 80 ± 0.15 2280: 80 ± 0.15							
Thickness maximum (mm)10	2.38							
Ordering Information	85GB	170GB	340GB	256GB	512GB	1TB	2TB	
M.2 2230-S3-M	SDBPTPZ-085G-XI	SDBPTPZ-170G-XI	SDBPTPZ-340G-2	XI SDBPTPZ-256G-XI	SDBPTPZ-512G-X	I SDBPTPZ-1T00-XI	N/A	
M.2 2280-S3-M	SDBPNPZ-085G-XI	SDBPNPZ-170G-XI	SDBPNPZ-340G-	XI SDBPNPZ-256G-XI	SDBPNPZ-512G-X	I SDBPNPZ-1T00-XI	SDBPNPZ-2T00->	
PCI Express 3.0 up to four lanes, and a bit rr x1, x2 and x4. NVM Express version 1.4 The capacities are based on IDEMA Standa gigabyte (GB) is equal to one billion bytes . capacity may be less due to operating env Test Conditions: burst performance is meas a secondary drive in desktop with Intel [®] Co 19041.208 with Microsoft StorNVMe driver. S specifications.	rd LBA 1-03. One megab and one terabyte (TB) is e ironment. 2TB is supporte sured by CrystalDiskMark re™ i7 7700 CPU, 8GB RA	yte is equal to one billion equal to one trillion bytes ed by M.2 2280 form fact 6.0.0, using 1000MB LBA M. OS: Windows 10 Pro 6	bytes, one ir bytes, one ir . Actual user °P or only. p range as 1 4-bit 20H1 te and sustained 7T	verage maximum power is me ommands for at least 10 secon terval is 1 second. Measured a eak power is the maximum in roccessing commands for at le thread. The sampling interval emperature variation. BW = Terabytes Written. Proji thout frequent idle.	nds, with a transfer size of at 25°C and can vary due istantaneous power cor east 10 seconds, with a l is 10µs. Measured at 25	of 128KB per command, QD= to input voltage and ambie isumption measured while t transfer size of 128KB per cc °C and can vary due to input	32 and 1 thread. Sampli nt temperature variation he SSD is continuously ommand, QD=32 and it voltage and ambient	

⁴ Test Conditions: sustained sequential performance is measured by FIO 1.97, using 100% LBA range as a secondary drive in Dell Precision 7820, with Intel[®] Xeon[®] Silver 4208 CPU, 16GB RAM. OS: Cent OS 8, Kernel 4.18.0–193.6.3.el8_2.x86_64.

⁷TBW = Terabytes Written. Projected endurance is calculated based on sustained sequential write operative without frequent idle. ⁸Based on Western Digital's internal calculation, using a prediction methodology in accordance with the Telcordia Special Report SR-332. The prediction is based on a Parts Stress Analysis, performed at a temperature of 40°C in a GB (ground, benign) environment with duty cycle of 12 hours per day.

⁶Operational temperature is defined such as -40°C refers to ambient temperature. +85°C refers to NAND BGA case temperature. When SMART composite temperature reported by the drive exceeds 85°C, thermal throttling will be initiated.

 10 The form factor complies with PCI Express M.2 Specification, rev. 4.0. Components Z height above PCB <=1.5mm (S3).

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